

HYBRID GROUND GRID FOR PRINTED CIRCUIT BOARD

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ABSTRACT OF THE DISCLOSURE

Electrical mounting boards and methods for their fabrication and use are disclosed herein. In particular, such mounting boards embodiments utilize hybrid ground lines interconnected through a substrate core to form multilayer ground grids. Such hybrid ground lines include groups of substantially parallel ground lines configured such that the groups of ground lines are positioned in transverse arrangement with other groups of ground lines formed on the same level. Such implementations have many uses, including, but not limited to, the ability to more efficiently route signal lines and connect electrical components on a circuit board.

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